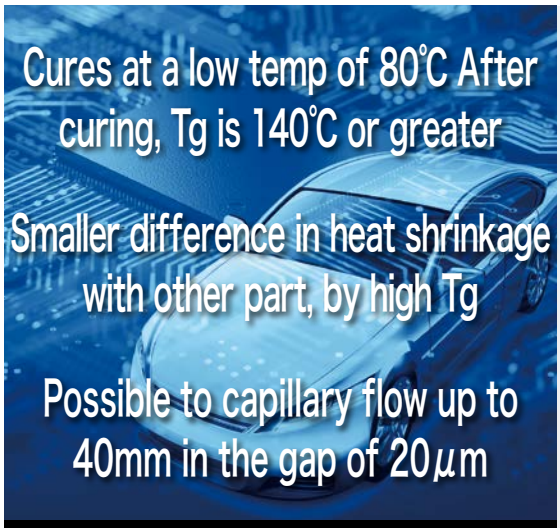
Panasonic INDUSTRY



Applications

IC Package/Automotive

Mount reinforcement of semiconductor packages and electronic parts for Automotive camera modules, Millimeter-wave radar modules, ECU, etc.

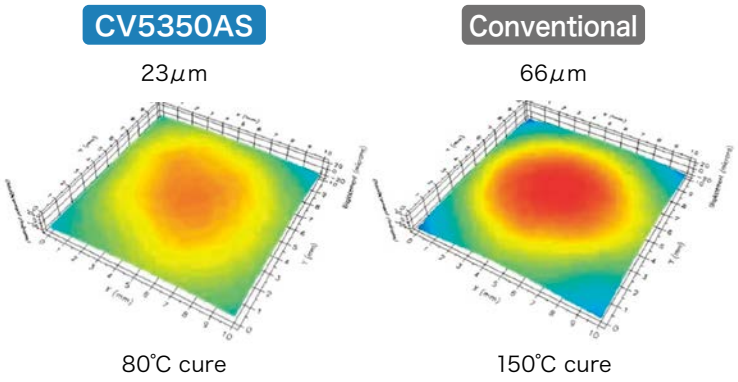
LEXCM DF

CV5350AS

Low-temperature curing secondary mounting Underfill materials

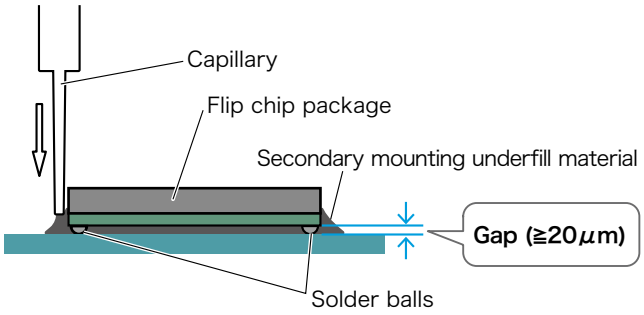
Cures at low temperatures and can be applied for mount-reinforcement of precision parts that need to be protected from higt temperatures. Improves the mounting reliability of automotive parts, for which high bonding strength is required.

Moire data at Room temperature

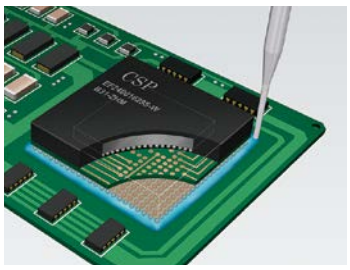


Suitable for mounting in areas with small gaps

Cross Section of a Circuited Board Being Mounted



Correspond to temperature cycle test under Automotive environment



Item	CV5350AS	Conventional
Temperature cycling test (TCT) -55℃⇔125℃"	1000 cycles Pass	300 cycles Pass

We also have "Corner reinforce type" suitable for partial reinforcement

General properties

Item	Unit	LEXCM DF CV5350AS
Minimum flow gap	μm	20
Viscosity (25℃)	mPa･s	4000
Glass transition temperature (Tg)	℃	150
C.T.E.1	ppm/℃	30
Elastic modulus (25℃)	GPa	10
Potential for reworking	–	Not possible

Please see our website for Notes before you use.

The above data are typical values and not guaranteed values.

industrial.panasonic.com/ww/electronic-materials

Panasonic Industry CV5350AS

Panasonic Industry Co., Ltd. Electronic Materials Business Division